

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

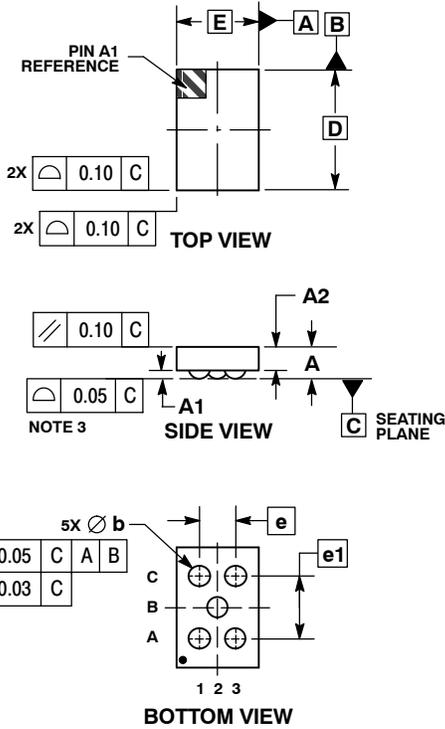
ON Semiconductor®



SCALE 4:1

WLCSP5, 1.34x0.91
CASE 567GN
ISSUE A

DATE 26 FEB 2013



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS	
	MIN	MAX
A	0.32	0.40
A1	0.08	0.12
A2	0.26 REF	
b	0.16	0.20
D	1.34 BSC	
E	0.91 BSC	
e	0.40 BSC	
e1	0.693 BSC	

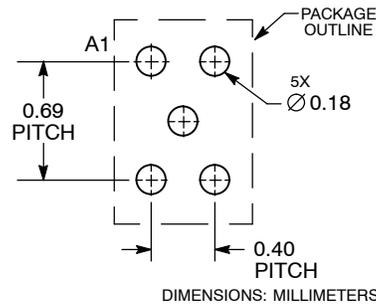
GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP5, 1.34X0.91	PAGE 1 OF 2

